



Special Issue on Composite Materials and Applications

Call for Papers

Composite Materials and Applications explores the design, fabrication, characterization, and practical use of materials formed by combining two or more distinct constituents to achieve tailored mechanical, thermal, electrical, or functional properties. Research in this area examines fiber-reinforced polymers, metal and ceramic matrix composites, hybrid systems, nanocomposites, bio-based materials, and advanced multifunctional structures. Key considerations include constituent compatibility, interfacial behavior, strength, stiffness, durability, fatigue resistance, fracture performance, and environmental stability. Emerging developments in additive manufacturing, sustainable material design, lightweight structures, smart composites, and recycling technologies are creating new opportunities for applications in aerospace, automotive engineering, construction, energy systems, electronics, and biomedical devices.

In this special issue, we intend to invite front-line researchers and authors to submit original research and review articles on exploring **Composite Materials and Applications**. Potential topics include, but are not limited to:

- Fiber reinforced composites
- Polymer matrix composites
- Metal matrix composites
- Ceramic matrix composites
- Nanocomposites
- Hybrid composites
- Bio-based composites
- Functional composites
- Smart composites
- Structural composites
- Composite manufacturing
- Interfacial engineering
- Composite characterization
- Mechanical performance
- Composite durability
- Composite recycling

Authors should read over the journal's [For Authors](#) carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal's [Paper Submission System](#).



Please kindly specify the “**Special Issue**” under your manuscript title. The research field “**Special Issue - *Composite Materials and Applications***” should be selected during your submission.

Special Issue Timetable:

Submission Deadline	January 12th, 2027
Publication Date	March 2027

Guest Editor:

For further questions or inquiries, please contact Editorial Assistant at
E-mail: papersubmissionmcy@gmail.com